



N-CHANNEL ENHANCEMENT MODE MOSFET

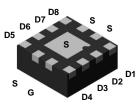
Features

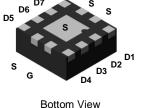
- Low Gate Charge
- $R_{DS(ON)}$: 280m Ω @ V_{GS} = 4.5V (Single MOSFET)
- 8 N-Channel MOSFET in 1 Device
- Common Source
- Small Footprint 1.5mm x 1.5mm
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

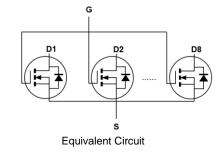
Mechanical Data

- Case: U-QFN1515-12
- Case Material Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3
- Terminal Connections: See Diagram
- Weight: 0.004 grams (Approximate)

U-QFN1515-12







Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|--------------|-------------------|
| DMN1250UFEL-7 | U-QFN1515-12 | 3,000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

U-QFN1515-12



A1 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014)M = Month (ex: 8 = August)

Date Code Key

| - and dodd . no | | | | | | | | | | | | |
|-----------------|------|-----|------|------|-----|------|------|-----|------|------|-----|------|
| Year | 2014 | | 2015 | 2016 | | 2017 | 2018 | | 2019 | 2020 | | 2021 |
| Code | В | | С | D | | Е | F | | G | Н | | |
| Month | Jan | Feb | Mar | Apr | Мау | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|------------------|------------|------|
| Drain-Source Voltage | V _{DSS} | 12 | V |
| Gate-Source Voltage | V _{GSS} | ±8 | V |
| Drain Current (Note 6) Continuous $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$ | l le | 2.0 1.6 | А |
| Pulsed Drain Current (Note 7) | I _{DM} | 10 | A |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Total Power Dissipation (Note 5) | P _D | 0.66 | W |
| Total Power Dissipation (Note 6) | P _D | 1.25 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | $R_{\theta JA}$ | 177 | °C/W |
| Thermal Resistance, Junction to Ambient (Note 6) | R _{0JA} | 100 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Notes:

- 5. Device mounted on 1"x1", FR-4 PC board with minimum recommended pad layout, and test with single MOSFET. 6. Device mounted on 1"x1", FR-4 PC board with 2 oz. copper, and test with single MOSFET.
- 7. Repetitive Rating, pulse width limited by junction temperature, and test with single MOSFET.

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|----------------------------------|-----|-----|------|------|--|--|
| STATIC CHARACTERISTICS | | | | | | | |
| Drain-Source Breakdown Voltage | | 12 | | _ | V | $I_D = 250 \mu A, V_{GS} = 0 V$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | | | 1 | μA | $V_{DS} = 12V, V_{GS} = 0V$ | |
| Gate-Body Leakage Current | I _{GSS} | _ | _ | ±100 | nA | $V_{DS} = 0V, V_{GS} = \pm 8V$ | |
| Gate Threshold Voltage | V _{GS(TH)} | 0.4 | _ | 1 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| Static Drain-Source On-Resistance (Note 8) | 5 | _ | 280 | 450 | mΩ | $V_{GS} = 4.5V, I_D = 0.2A$ | |
| Static Dialif-Source Off-Resistance (Note 6) | R _{DS(ON)} | _ | 360 | 550 | mΩ | $V_{GS} = 2.5V, I_D = 0.1A$ | |
| Forward Transfer Admittance | Y _{FS} | _ | 1 | _ | S | $V_{DS} = 6V, I_D = 0.2A$ | |
| Diode Forward Voltage (Note 8) | V _{SD} | _ | 0.8 | 1.0 | V | $I_S = 0.2A$, $V_{GS} = 0V$ | |
| DYNAMIC CHARACTERISTICS (Note 9) | DYNAMIC CHARACTERISTICS (Note 9) | | | | | | |
| Input Capacitance | C _{iss} | | 146 | 190 | pF | | |
| Output Capacitance | Coss | | 10 | 15 | pF | $V_{DS} = 6V, V_{GS} = 0V$ -f = 1.0MHz | |
| Reverse Transfer Capacitance | C _{rss} | _ | 8 | 13 | pF | 1 = 1.0001112 | |
| Gate Resistance | R_{G} | _ | 2.4 | _ | Ω | $V_{GS} = 0V$, $V_{DS} = 0V$, $f = 1MHz$ | |
| SWITCHING CHARACTERISTICS (Note 9) | | | | | | | |
| Total Gate Charge | Qg | | 1.3 | 1.9 | nC | | |
| Gate-Source Charge | Qgs | | 0.3 | _ | nC | $V_{GS} = 4.5V$, $V_{DS} = 6V$, $I_D = 0.2A$ | |
| Gate-Drain Charge | Q_{gd} | _ | 0.1 | _ | nC | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 1.9 | 2.7 | nS | | |
| Turn-On Rise Time | | | 1.3 | _ | nS | $V_{DD} = 6V, V_{GS} = 4.5V,$ | |
| Turn-Off Delay Time | t _{D(OFF)} | | 7.5 | 11 | nS | $R_L = 22\Omega$, $R_G = 6\Omega$ | |
| Turn-Off Fall Time | t _F | | 1.0 | _ | nS | | |

8. Test pulse width t = 300ms, test with single MOSFET. Notes:

^{9.} Guaranteed by design with single MOSFET, not subject to production testing.



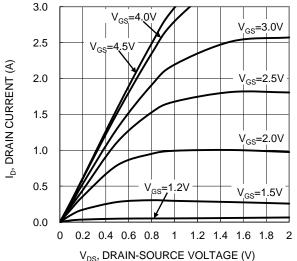


Figure 1. Typical Output Characteristic

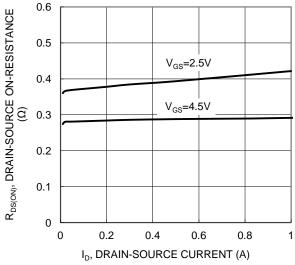


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

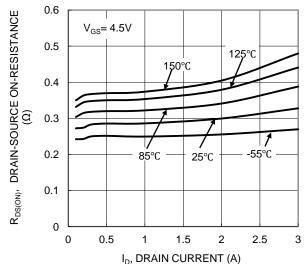
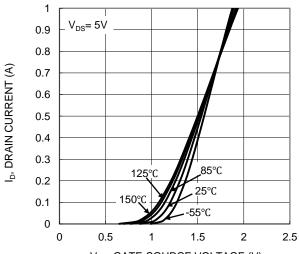


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic

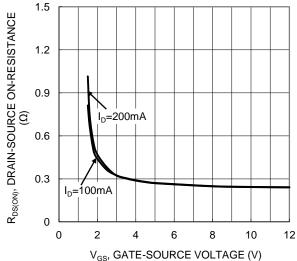


Figure 4. Typical Transfer Characteristic

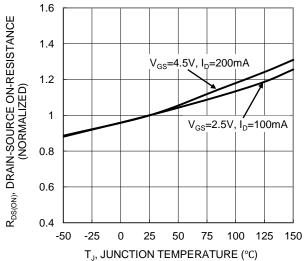


Figure 6. On-Resistance Variation with Temperature



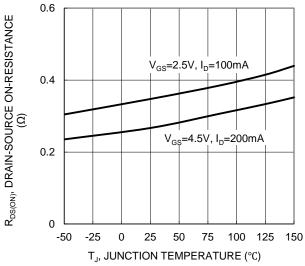
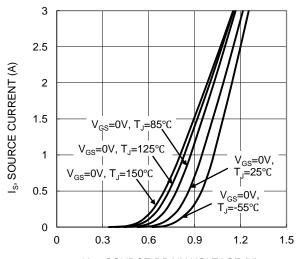
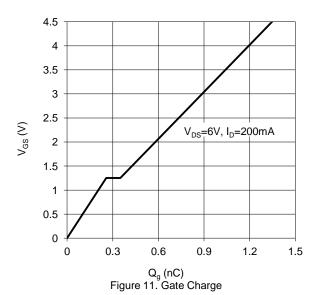


Figure 7. On-Resistance Variation with Temperature

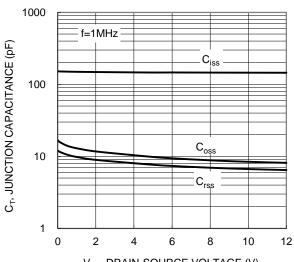


V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current

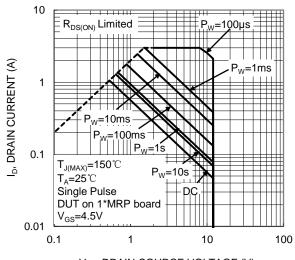


1.2 $V_{GS(TH)}, \, GATE \, THRESHOLD \, VOLTAGE \, (V)$ 1 I_D=1mA 8.0 $I_{D} = 250 \mu A$ 0.6 0.4 0 -50 -25 25 50 75 100 125 150 T_J, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Junction Temperature

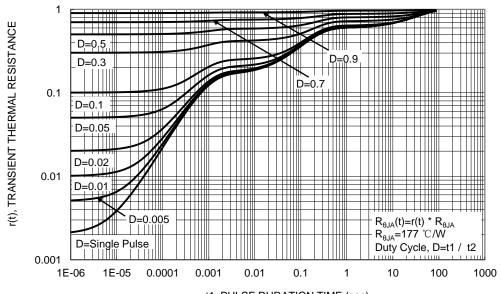


V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 10. Typical Junction Capacitance



 $V_{\rm DS}$, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area





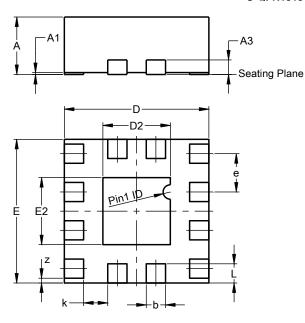
t1, PULSE DURATION TIME (sec) Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

U-QFN1515-12

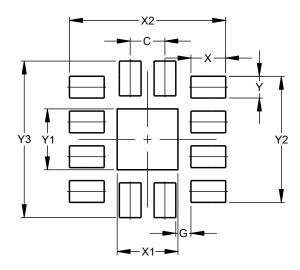


| U-QFN1515-12 | | | | | | | |
|----------------------|-----------|------|-------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.57 | 0.63 | 0.60 | | | | |
| A1 | 0.00 | 0.05 | 0.02 | | | | |
| A3 | 0.152 BSC | | | | | | |
| b | 0.15 | 0.25 | 0.20 | | | | |
| D | 1.45 | 1.55 | 1.50 | | | | |
| D2 | 0.60 | 0.80 | 0.70 | | | | |
| Е | 1.45 | 1.55 | 1.50 | | | | |
| E2 | 0.60 | 0.80 | 0.70 | | | | |
| е | 0.40 BSC | | | | | | |
| L | 0.15 | 0.25 | 0.20 | | | | |
| k | | | 0.25 | | | | |
| Z | | | 0.050 | | | | |
| All Dimensions in mm | | | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

U-QFN1515-12



| Dimensions | Value (in mm) |
|------------|------------------|
| С | 0.400 |
| G | 0.175 |
| Х | 0.400 |
| X1 | 0.700 |
| X2 | 1.800 |
| Υ | 0.250 |
| Y1 | 0.700 |
| Y2 | 1.450 |
| Y3 | 1 800 |



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